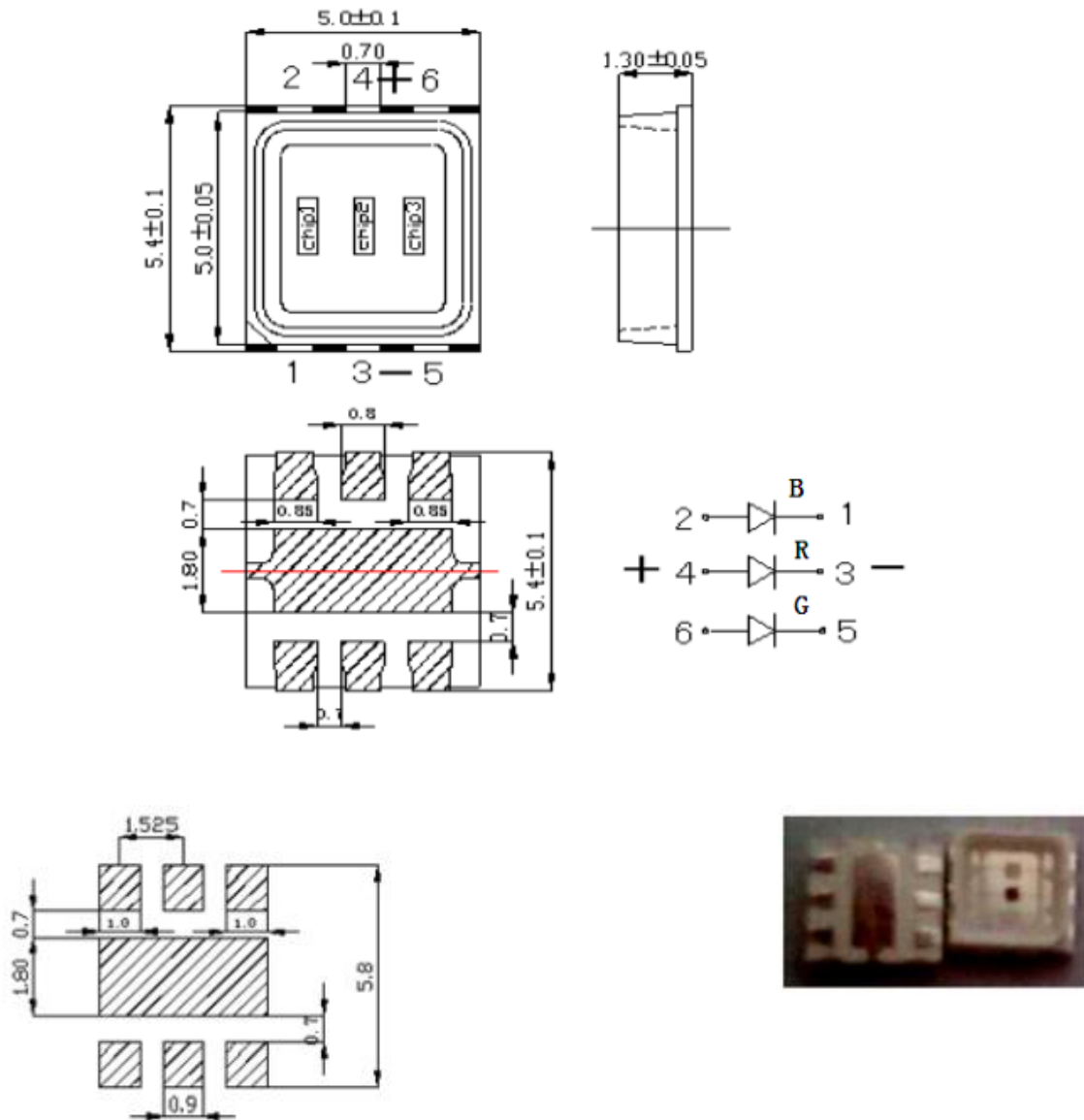


Package Dimensions:



Notes

- All dimensions are in millimeters (inches).
- Tolerance is $\pm 0.25\text{mm}$ (.010") unless otherwise noted.
- Protruded resin under flange is 1.0mm(.04") max.
- Lead spacing is measured where the leads emerge from the package.
- Specifications are subject to change without notice.

Absolute Maximum Ratings at TA=25°C

Parameter	Value			Unit
Power Dissipation	R 1	G 2	B 2	W
Pulsed Forward Current (1/10 Duty Cycle, 0.1ms Pulse width)	1150			mA
Continuous Forward Current	350*3			mA
Derating Linear from 50°C	0.4			mA/°C
Reverse Voltage	5			V
Operation Temperature Range				+40°C to +85°C
Storage Temperature Range				-40°C to +85°C
Lead Soldering Temperature				260°C for 5 seconds

Electrical / Optical Characteristics at TA=25°C

Parameter	Symbol	Min.	Typ.	Max	Unit	Test Condition
Luminous Intensity	R	25	30	--	lm	IF=350*3mA Note 1
	G	60	65	--		
	B	16	20	--		
Viewing Angle	2θ ½	--	120	--	deg	Note 2
Wavelength	R	620	--	630	nm	IF=350*3mA Note 4
	G	520	--	535		
	B	460	--	470		
Forward Voltage	R	1.8	--	2.4	V	IF=350*3mA
	G	2.8	--	3.4		
	B	2.8	--	3.4		
Reverse Current	IR	--	--	5	µA	VR=5V

Notes:

Luminous intensity is measured with a light sensor and filter combination that approximates the CIE (Commission International De L'Eclairage) eye-response curve. 1/2 is the off-axis angle at which the luminous intensity is half the axial luminous and intensity. The dominant wavelength, λ d is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device. The IV guarantee should be added ± 15%

**Intensity BIN limit (IF=350*3mA)****Red**

Bin Code	Min (lm)	Typ. (lm)
A	25	30

Green

Bin Code	Min (lm)	Typ. (lm)
A	60	65

Blue

Bin Code	Min (lm)	Typ. (lm)
A	16	20

Color BIN limit (IF=350*3mA)**Red**

Bin Code	Min (nm)	Max (nm)
A	620	625
B	625	630

Green

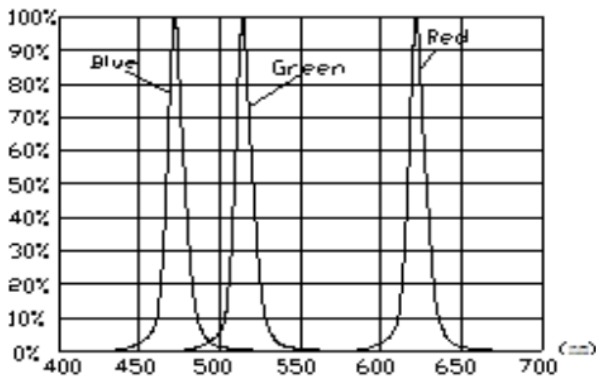
Bin Code	Min (nm)	Max (nm)
A	520	525
B	525	530
C	530	535

Blue

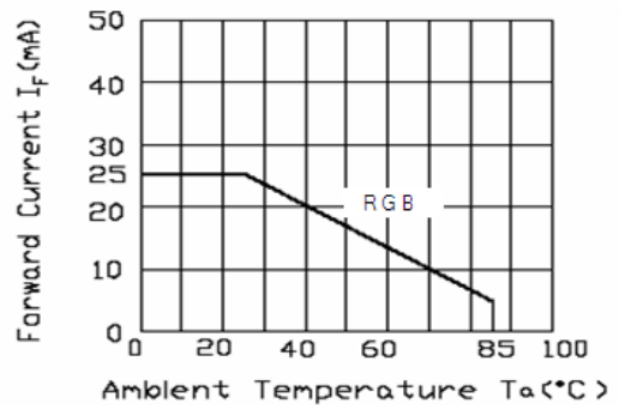
Bin Code	Min (nm)	Max (nm)
A	460	465
B	465	470

Optical Characteristics

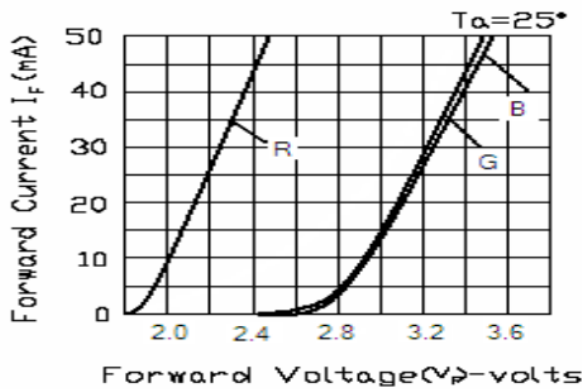
光谱曲线图



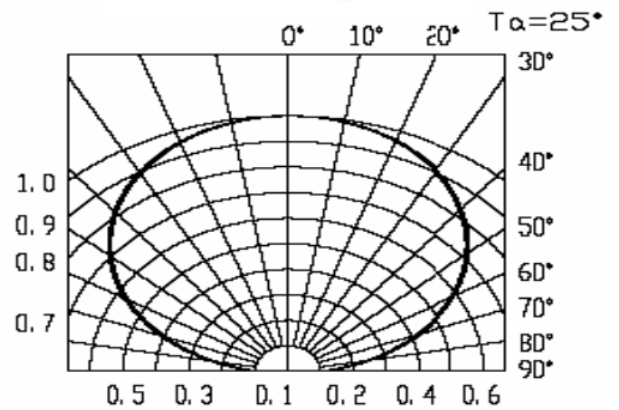
电流与温度关系曲线图



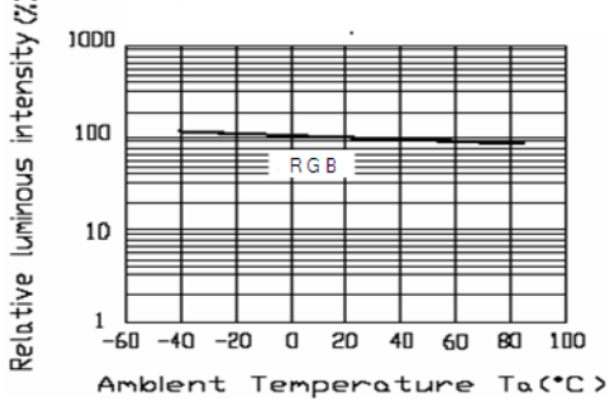
电压电流关系曲线图



发光角度图



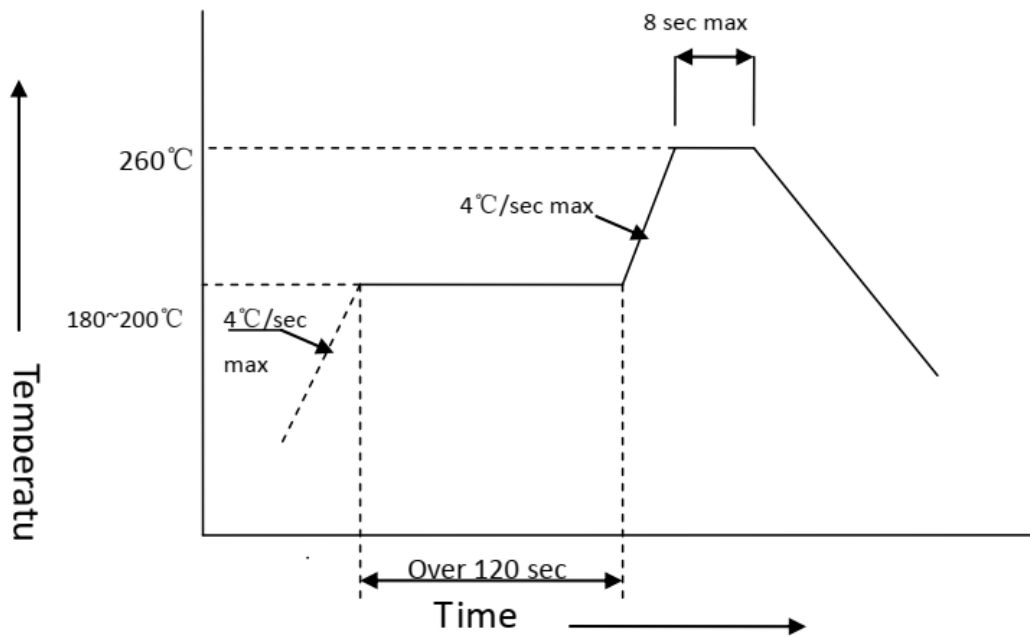
亮度/流明与温度的关系曲线图



Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and Second soldering process.

1>Lead Solder



2>Lead-Free Solder

